



FG1156 - 63/37 (Sn/Pb) Solder Balls
 FGG1156 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	\approx	2.33	2.60	2
A ₁	0.40	0.50	0.60	
D/E	35.00 BSC			
D ₁ /E ₁	33.00 REF			
e	1.00 BSC			
phi _b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.35	
ddd	\approx	\approx	0.30	
eee	\approx	\approx	0.10	
L	\approx	\approx	33.05	
M	34			
REF.	JEDEC MS-034-AAR			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. LAND PAD OPENING - SOLDER MASK DEFINED ϕ 0.485mm (0.019")

1156-BALL FINE-PITCH BGA, 1.00MM PITCH (FG1156/FGG1156)